

EAST Search History

Ref #	Hits	Search Query	DBs	Default Operator	Plurals	Time Stamp
L1	46	("20020050635" "20020077467" "20020109236" "20020109236" "20020135062" "4313126" "4402761" "4456888" "4599704" "4313126" "4402761" "4456888" "4599704" "4986861" "5523628" "5706578" "5767009" "5825080" "0050635" "5156997" "5206186" "5445994" "5523628" "5821138" "5923087" "6717244" "6441478" "6717244" "0077467").PN.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/08/03 09:31
L2	10	("4285780" "5072075" "5274912" "5590461").PN. OR ("5706578").URPN.	US-PGPUB; USPAT; USOCR	OR	ON	2006/08/03 09:31
L3	9	("3489954" "3533023" "4939568" "5311059" "5401687" "5438212" "5721454").PN.	US-PGPUB; USPAT; USOCR	OR	ON	2006/08/03 09:31
L4	92	("3787252" "4074342" "4500905" "4523211" "4688069" "4761681" "4807021").PN. OR ("4939568").URPN.	US-PGPUB; USPAT; USOCR	OR	ON	2006/08/03 09:31
L5	1	"20040124538".pn.	US-PGPUB; USPAT; USOCR	OR	ON	2006/08/03 09:31
L6	1264	three near2 dimensional near1 (IC integrated adj circuit chip die wafer semiconductor) and "257"/\$.ccls.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/08/03 09:31
L7	133	(three near2 dimensional near1 (IC integrated adj circuit chip die wafer semiconductor)).ab. and "257"/\$.ccls.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/08/03 09:31
L8	3	("5753536" "5902118" "6322903").PN.	US-PGPUB; USPAT; USOCR	OR	ON	2006/08/03 09:31
L9	5	("5753536" "5902118" "6322903").PN. OR ("6525415").URPN.	US-PGPUB; USPAT; USOCR	OR	ON	2006/08/03 09:31
L10	8	("4461922" "4481378" "5398200" "5401983" "5612552" "5731621" "5747846" "5852310").PN.	US-PGPUB; USPAT; USOCR	OR	ON	2006/08/03 09:31
L11	3	wiring adj interconnect with copper with transistor	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/08/03 09:31

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L12	247	interconnect with copper with transistor	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/08/03 09:31
L13	172	interconnect near3 copper with transistor	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/08/03 09:31
L14	81	interconnect near3 copper with transistor	USPAT	OR	ON	2006/08/03 09:31
L15	1	"4939568".pn.	USPAT	OR	ON	2006/08/03 09:31
L16	1	"20040124538".pn.	US-PGPUB; USPAT; USOCR	OR	ON	2006/08/03 09:31
L17	46	("20020050635" "20020077467" "20020109236" "20020109236" "20020135062" "4313126" "4402761" "4456888" "4599704" "4313126" "4402761" "4456888" "4599704" "4986861" "5523628" "5706578" "5767009" "5825080" "0050635" "5156997" "5206186" "5445994" "5523628" "5821138" "5923087" "6717244" "6441478" "6717244" "0077467").PN.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/08/03 09:31
L18	10	("4285780" "5072075" "5274912" "5590461").PN. OR ("5706578").URPN.	US-PGPUB; USPAT; USOCR	OR	ON	2006/08/03 09:31
L19	9	("3489954" "3533023" "4939568" "5311059" "5401687" "5438212" "5721454").PN.	US-PGPUB; USPAT; USOCR	OR	ON	2006/08/03 09:31
L20	92	("3787252" "4074342" "4500905" "4523211" "4688069" "4761681" "4807021").PN. OR ("4939568").URPN.	US-PGPUB; USPAT; USOCR	OR	ON	2006/08/03 09:31
L21	66	(three near2 dimensional near1 (IC integrated adj circuit chip die wafer semiconductor)).ab. and "438"/\$.ccls.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/08/03 09:31
L22	1264	three near2 dimensional near1 (IC integrated adj circuit chip die wafer semiconductor) and "257"/\$.ccls.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/08/03 09:31

EAST Search History

L23	247	interconnect with copper with transistor	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/08/03 09:31
L24	66	(three near2 dimensional near1 (IC integrated adj circuit chip die wafer semiconductor)).ab. and "438"/\$. ccls.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/08/03 09:31
L25	1	"20040124538".pn.	US-PGPUB; USPAT; USOCR	OR	ON	2006/08/03 09:31
L26	1	"4939568".pn.	USPAT	OR	ON	2006/08/03 09:31
L27	1	"20040124538".pn.	US-PGPUB; USPAT; USOCR	OR	ON	2006/08/03 09:31
L28	46	("20020050635" "20020077467" "20020109236" "20020109236" "20020135062" "4313126" "4402761" "4456888" "4599704" "4313126" "4402761" "4456888" "4599704" "4986861" "5523628" "5706578" "5767009" "5825080" "0050635" "5156997" "5206186" "5445994" "5523628" "5821138" "5923087" "6717244" "6441478" "6717244" "0077467").PN.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/08/03 09:31
L29	10	("4285780" "5072075" "5274912" "5590461").PN. OR ("5706578").URPN.	US-PGPUB; USPAT; USOCR	OR	ON	2006/08/03 09:31
L30	9	("3489954" "3533023" "4939568" "5311059" "5401687" "5438212" "5721454").PN.	US-PGPUB; USPAT; USOCR	OR	ON	2006/08/03 09:31
L31	92	("3787252" "4074342" "4500905" "4523211" "4688069" "4761681" "4807021").PN. OR ("4939568").URPN.	US-PGPUB; USPAT; USOCR	OR	ON	2006/08/03 09:31
L32	3	("5753536" "5902118" "6322903").PN.	US-PGPUB; USPAT; USOCR	OR	ON	2006/08/03 09:31
L33	5	("5753536" "5902118" "6322903").PN. OR ("6525415").URPN.	US-PGPUB; USPAT; USOCR	OR	ON	2006/08/03 09:31
L34	8	("4461922" "4481378" "5398200" "5401983" "5612552" "5731621" "5747846" "5852310").PN.	US-PGPUB; USPAT; USOCR	OR	ON	2006/08/03 09:31

EAST Search History

L35	3	wiring adj interconnect with copper with transistor	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/08/03 09:31
L36	81	interconnect near3 copper with transistor	USPAT	OR	ON	2006/08/03 09:31
L37	46	("20020050635" "20020077467" "20020109236" "20020109236" "20020135062" "4313126" "4402761" "4456888" "4599704" "4313126" "4402761" "4456888" "4599704" "4986861" "5523628" "5706578" "5767009" "5825080" "0050635" "5156997" "5206186" "5445994" "5523628" "5821138" "5923087" "6717244" "6441478" "6717244" "0077467").PN.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/08/03 09:31
L38	10	("4285780" "5072075" "5274912" "5590461").PN. OR ("5706578").URPN.	US-PGPUB; USPAT; USOCR	OR	ON	2006/08/03 09:31
L39	9	("3489954" "3533023" "4939568" "5311059" "5401687" "5438212" "5721454").PN.	US-PGPUB; USPAT; USOCR	OR	ON	2006/08/03 09:31
L40	92	("3787252" "4074342" "4500905" "4523211" "4688069" "4761681" "4807021").PN. OR ("4939568").URPN.	US-PGPUB; USPAT; USOCR	OR	ON	2006/08/03 09:31
L41	133	(three near2 dimensional near1 (IC integrated adj circuit chip die wafer semiconductor)).ab. and "257"/\$.ccls.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/08/03 09:31
L42	172	interconnect near3 copper with transistor	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/08/03 09:31
L43	2	("5940683").PN.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/08/03 09:31
L44	1264	three near2 dimensional near1 (IC integrated adj circuit chip die wafer semiconductor) and "257"/\$.ccls.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/08/03 09:31

EAST Search History

L45	247	interconnect with copper with transistor	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/08/03 09:31
L46	66	(three near2 dimensional near1 (IC integrated adj circuit chip die wafer semiconductor)).ab. and "438"/\$.ccls.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/08/03 09:31
L47	1264	three near2 dimensional near1 (IC integrated adj circuit chip die wafer semiconductor) and "257"/\$.ccls.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/08/03 09:31
L48	247	interconnect with copper with transistor	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/08/03 09:31
L49	66	(three near2 dimensional near1 (IC integrated adj circuit chip die wafer semiconductor)).ab. and "438"/\$.ccls.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/08/03 09:31
L50	1	"20040124538".pn.	US-PGPUB; USPAT; USOCR	OR	ON	2006/08/03 09:31
L51	1	"4939568".pn.	USPAT	OR	ON	2006/08/03 09:31
L52	1	"20040124538".pn.	US-PGPUB; USPAT; USOCR	OR	ON	2006/08/03 09:31
L53	1	"20040124538".pn.	US-PGPUB; USPAT; USOCR	OR	ON	2006/08/03 09:31
L54	1	"4939568".pn.	USPAT	OR	ON	2006/08/03 09:31
L55	1	"20040124538".pn.	US-PGPUB; USPAT; USOCR	OR	ON	2006/08/03 09:31
L56	46	("20020050635" "20020077467" "20020109236" "20020109236" "20020135062" "4313126" "4402761" "4456888" "4599704" "4313126" "4402761" "4456888" "4599704" "4986861" "5523628" "5706578" "5767009" "5825080" "0050635" "5156997" "5206186" "5445994" "5523628" "5821138" "5923087" "6717244" "6441478" "6717244" "0077467").PN.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/08/03 09:31

EAST Search History

L57	10	("4285780" "5072075" "5274912" "5590461").PN. OR ("5706578").URPN.	US-PGPUB; USPAT; USOCR	OR	ON	2006/08/03 09:31
L58	9	("3489954" "3533023" "4939568" "5311059" "5401687" "5438212" "5721454").PN.	US-PGPUB; USPAT; USOCR	OR	ON	2006/08/03 09:31
L59	92	("3787252" "4074342" "4500905" "4523211" "4688069" "4761681" "4807021").PN. OR ("4939568").URPN.	US-PGPUB; USPAT; USOCR	OR	ON	2006/08/03 09:31
L60	3	("5753536" "5902118" "6322903").PN.	US-PGPUB; USPAT; USOCR	OR	ON	2006/08/03 09:31
L61	5	("5753536" "5902118" "6322903").PN. OR ("6525415").URPN.	US-PGPUB; USPAT; USOCR	OR	ON	2006/08/03 09:31
L62	8	("4461922" "4481378" "5398200" "5401983" "5612552" "5731621" "5747846" "5852310").PN.	US-PGPUB; USPAT; USOCR	OR	ON	2006/08/03 09:31
L63	3	wiring adj interconnect with copper with transistor	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/08/03 09:31
L64	81	interconnect near3 copper with transistor	USPAT	OR	ON	2006/08/03 09:31
L65	46	("20020050635" "20020077467" "20020109236" "20020109236" "20020135062" "4313126" "4402761" "4456888" "4599704" "4313126" "4402761" "4456888" "4599704" "4986861" "5523628" "5706578" "5767009" "5825080" "0050635" "5156997" "5206186" "5445994" "5523628" "5821138" "5923087" "6717244" "6441478" "6717244" "0077467").PN.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/08/03 09:31
L66	10	("4285780" "5072075" "5274912" "5590461").PN. OR ("5706578").URPN.	US-PGPUB; USPAT; USOCR	OR	ON	2006/08/03 09:31
L67	9	("3489954" "3533023" "4939568" "5311059" "5401687" "5438212" "5721454").PN.	US-PGPUB; USPAT; USOCR	OR	ON	2006/08/03 09:31
L68	92	("3787252" "4074342" "4500905" "4523211" "4688069" "4761681" "4807021").PN. OR ("4939568").URPN.	US-PGPUB; USPAT; USOCR	OR	ON	2006/08/03 09:31

EAST Search History

L69	46	("20020050635" "20020077467" "20020109236" "20020109236" "20020135062" "4313126" "4402761" "4456888" "4599704" "4313126" "4402761" "4456888" "4599704" "4986861" "5523628" "5706578" "5767009" "5825080" "0050635" "5156997" "5206186" "5445994" "5523628" "5821138" "5923087" "6717244" "6441478" "6717244" "0077467").PN.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/08/03 09:31
L70	10	("4285780" "5072075" "5274912" "5590461").PN. OR ("5706578").URPN.	US-PGPUB; USPAT; USOCR	OR	ON	2006/08/03 09:31
L71	9	("3489954" "3533023" "4939568" "5311059" "5401687" "5438212" "5721454").PN.	US-PGPUB; USPAT; USOCR	OR	ON	2006/08/03 09:31
L72	92	("3787252" "4074342" "4500905" "4523211" "4688069" "4761681" "4807021").PN. OR ("4939568").URPN.	US-PGPUB; USPAT; USOCR	OR	ON	2006/08/03 09:31
L73	3	("5753536" "5902118" "6322903").PN.	US-PGPUB; USPAT; USOCR	OR	ON	2006/08/03 09:31
L74	5	("5753536" "5902118" "6322903").PN. OR ("6525415").URPN.	US-PGPUB; USPAT; USOCR	OR	ON	2006/08/03 09:31
L75	8	("4461922" "4481378" "5398200" "5401983" "5612552" "5731621" "5747846" "5852310").PN.	US-PGPUB; USPAT; USOCR	OR	ON	2006/08/03 09:31
L76	3	wiring adj interconnect with copper with transistor	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/08/03 09:31
L77	81	interconnect near3 copper with transistor	USPAT	OR	ON	2006/08/03 09:31
L78	46	("20020050635" "20020077467" "20020109236" "20020109236" "20020135062" "4313126" "4402761" "4456888" "4599704" "4313126" "4402761" "4456888" "4599704" "4986861" "5523628" "5706578" "5767009" "5825080" "0050635" "5156997" "5206186" "5445994" "5523628" "5821138" "5923087" "6717244" "6441478" "6717244" "0077467").PN.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/08/03 09:31
L79	10	("4285780" "5072075" "5274912" "5590461").PN. OR ("5706578").URPN.	US-PGPUB; USPAT; USOCR	OR	ON	2006/08/03 09:31
L80	9	("3489954" "3533023" "4939568" "5311059" "5401687" "5438212" "5721454").PN.	US-PGPUB; USPAT; USOCR	OR	ON	2006/08/03 09:31

EAST Search History

L81	92	("3787252" "4074342" "4500905" "4523211" "4688069" "4761681" "4807021").PN. OR ("4939568").URPN.	US-PGPUB; USPAT; USOCR	OR	ON	2006/08/03 09:31
L82	2	("5940683").PN.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/08/03 09:31
L83	133	(three near2 dimensional near1 (IC integrated adj circuit chip die wafer semiconductor)).ab. and "257"/\$.ccls.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/08/03 09:31
L84	172	interconnect near3 copper with transistor	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/08/03 09:31
L85	133	(three near2 dimensional near1 (IC integrated adj circuit chip die wafer semiconductor)).ab. and "257"/\$.ccls.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/08/03 09:31
L86	172	interconnect near3 copper with transistor	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/08/03 09:31
L87	144	andujar.xa.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/08/03 09:31
L88	3	wiring adj interconnect with copper with transistor	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/08/03 09:31
L89	8	("4461922" "4481378" "5398200" "5401983" "5612552" "5731621" "5747846" "5852310").PN.	US-PGPUB; USPAT; USOCR	OR	ON	2006/08/03 09:31
L90	5	("5753536" "5902118" "6322903").PN. OR ("6525415").URPN.	US-PGPUB; USPAT; USOCR	OR	ON	2006/08/03 09:31

EAST Search History

L91	3	("5753536" "5902118" "6322903").PN.	US-PGPUB; USPAT; USOCR	OR	ON	2006/08/03 09:31
L92	92	("3787252" "4074342" "4500905" "4523211" "4688069" "4761681" "4807021").PN. OR ("4939568").URPN.	US-PGPUB; USPAT; USOCR	OR	ON	2006/08/03 09:31
L93	9	("3489954" "3533023" "4939568" "5311059" "5401687" "5438212" "5721454").PN.	US-PGPUB; USPAT; USOCR	OR	ON	2006/08/03 09:31
L94	46	("20020050635" "20020077467" "20020109236" "20020109236" "20020135062" "4313126" "4402761" "4456888" "4599704" "4313126" "4402761" "4456888" "4599704" "4986861" "5523628" "5706578" "5767009" "5825080" "0050635" "5156997" "5206186" "5445994" "5523628" "5821138" "5923087" "6717244" "6441478" "6717244" "0077467").PN.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/08/03 09:31
L95	10	("4285780" "5072075" "5274912" "5590461").PN. OR ("5706578").URPN.	US-PGPUB; USPAT; USOCR	OR	ON	2006/08/03 09:31
L96	247	interconnect with copper with transistor	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/08/03 09:31
L97	66	(three near2 dimensional near1 (IC integrated adj circuit chip die wafer semiconductor)).ab. and "438"/\$.ccls.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/08/03 09:31
L98	1	"20040124538".pn.	US-PGPUB; USPAT; USOCR	OR	ON	2006/08/03 09:31
L99	1	"4939568".pn.	USPAT	OR	ON	2006/08/03 09:31
L100	1	"20040124538".pn.	US-PGPUB; USPAT; USOCR	OR	ON	2006/08/03 09:31
L101	46	("20020050635" "20020077467" "20020109236" "20020109236" "20020135062" "4313126" "4402761" "4456888" "4599704" "4313126" "4402761" "4456888" "4599704" "4986861" "5523628" "5706578" "5767009" "5825080" "0050635" "5156997" "5206186" "5445994" "5523628" "5821138" "5923087" "6717244" "6441478" "6717244" "0077467").PN.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/08/03 09:31

EAST Search History

L102	10	("4285780" "5072075" "5274912" "5590461").PN. OR ("5706578").URPN.	US-PGPUB; USPAT; USOCR	OR	ON	2006/08/03 09:31
L103	9	("3489954" "3533023" "4939568" "5311059" "5401687" "5438212" "5721454").PN.	US-PGPUB; USPAT; USOCR	OR	ON	2006/08/03 09:31
L104	92	("3787252" "4074342" "4500905" "4523211" "4688069" "4761681" "4807021").PN. OR ("4939568").URPN.	US-PGPUB; USPAT; USOCR	OR	ON	2006/08/03 09:31
L105	10	("4285780" "5072075" "5274912" "5590461").PN. OR ("5706578").URPN.	US-PGPUB; USPAT; USOCR	OR	ON	2006/08/03 09:31
L106	46	("20020050635" "20020077467" "20020109236" "20020109236" "20020135062" "4313126" "4402761" "4456888" "4599704" "4313126" "4402761" "4456888" "4599704" "4986861" "5523628" "5706578" "5767009" "5825080" "0050635" "5156997" "5206186" "5445994" "5523628" "5821138" "5923087" "6717244" "6441478" "6717244" "0077467").PN.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/08/03 09:31
L107	247	interconnect with copper with transistor	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/08/03 09:31
L108	133	(three near2 dimensional near1 (IC integrated adj circuit chip die wafer semiconductor)).ab. and "257"/\$.ccls.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/08/03 09:31
L109	92	("3787252" "4074342" "4500905" "4523211" "4688069" "4761681" "4807021").PN. OR ("4939568").URPN.	US-PGPUB; USPAT; USOCR	OR	ON	2006/08/03 09:31
L110	10	("3904442" "4275410" "4612083" "4760335" "4761681" "5386142" "5474458" "5528080" "5608264" "5973368").PN. OR ("6661086").URPN.	US-PGPUB; USPAT; USOCR	OR	ON	2006/08/03 09:31
L111	3	("5753536" "5902118" "6322903").PN.	US-PGPUB; USPAT; USOCR	OR	ON	2006/08/03 09:31
L112	92	("3787252" "4074342" "4500905" "4523211" "4688069" "4761681" "4807021").PN. OR ("4939568").URPN.	US-PGPUB; USPAT; USOCR	OR	ON	2006/08/03 09:31

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L113	3	wiring adj interconnect with copper with transistor	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/08/03 09:31
L114	9	("3489954" "3533023" "4939568" "5311059" "5401687" "5438212" "5721454").PN.	US-PGPUB; USPAT; USOCR	OR	ON	2006/08/03 09:31
L115	1264	three near2 dimensional near1 (IC integrated adj circuit chip die wafer semiconductor) and "257"/\$.ccls.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/08/03 09:31
L116	66	(three near2 dimensional near1 (IC integrated adj circuit chip die wafer semiconductor)).ab. and "438"/\$.ccls.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/08/03 09:31
L117	1	"20040124538".pn.	US-PGPUB; USPAT; USOCR	OR	ON	2006/08/03 09:31
L118	1	"20040124538".pn.	US-PGPUB; USPAT; USOCR	OR	ON	2006/08/03 09:31
L119	8	("4461922" "4481378" "5398200" "5401983" "5612552" "5731621" "5747846" "5852310").PN.	US-PGPUB; USPAT; USOCR	OR	ON	2006/08/03 09:31
L120	5	("5753536" "5902118" "6322903").PN. OR ("6525415").URPN.	US-PGPUB; USPAT; USOCR	OR	ON	2006/08/03 09:31
L121	172	interconnect near3 copper with transistor	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/08/03 09:31
L122	81	interconnect near3 copper with transistor	USPAT	OR	ON	2006/08/03 09:31
L123	1	"4939568".pn.	USPAT	OR	ON	2006/08/03 09:31
L124	1264	three near2 dimensional near1 (IC integrated adj circuit chip die wafer semiconductor) and "257"/\$.ccls.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/08/03 09:31

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L125	1264	three near2 dimensional near1 (IC integrated adj circuit chip die wafer semiconductor) and "257"/\$.ccls.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/08/03 09:31
L126	66	(three near2 dimensional near1 (IC integrated adj circuit chip die wafer semiconductor)).ab. and "438"/\$.ccls.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/08/03 09:31
L127	1	"20040124538".pn.	US-PGPUB; USPAT; USOCR	OR	ON	2006/08/03 09:31
L128	3	wiring adj interconnect with copper with transistor	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/08/03 09:31
L129	81	interconnect near3 copper with transistor	USPAT	OR	ON	2006/08/03 09:31
L130	46	("20020050635" "20020077467" "20020109236" "20020109236" "20020135062" "4313126" "4402761" "4456888" "4599704" "4313126" "4402761" "4456888" "4599704" "4986861" "5523628" "5706578" "5767009" "5825080" "0050635" "5156997" "5206186" "5445994" "5523628" "5821138" "5923087" "6717244" "6441478" "6717244" "0077467").PN.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/08/03 09:31
L131	10	("4285780" "5072075" "5274912" "5590461").PN. OR ("5706578").URPN.	US-PGPUB; USPAT; USOCR	OR	ON	2006/08/03 09:31
L132	9	("3489954" "3533023" "4939568" "5311059" "5401687" "5438212" "5721454").PN.	US-PGPUB; USPAT; USOCR	OR	ON	2006/08/03 09:31
L133	92	("3787252" "4074342" "4500905" "4523211" "4688069" "4761681" "4807021").PN. OR ("4939568").URPN.	US-PGPUB; USPAT; USOCR	OR	ON	2006/08/03 09:31
L134	133	(three near2 dimensional near1 (IC integrated adj circuit chip die wafer semiconductor)).ab. and "257"/\$.ccls.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/08/03 09:32

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L135	172	interconnect near3 copper with transistor	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/08/03 09:32
L136	66	(three near2 dimensional near1 (IC integrated adj circuit chip die wafer semiconductor)).ab. and "438"/\$.ccls.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/08/03 09:32
L137	247	interconnect with copper with transistor	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/08/03 09:32
L138	2	("5940683").PN.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/08/03 09:32
L139	1264	three near2 dimensional near1 (IC integrated adj circuit chip die wafer semiconductor) and "257"/\$.ccls.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/08/03 09:32
L140	247	interconnect with copper with transistor	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/08/03 09:32
L141	10	("4285780" "5072075" "5274912" "5590461").PN. OR ("5706578").URPN.	US-PGPUB; USPAT; USOCR	OR	ON	2006/08/03 09:32
L142	81	interconnect near3 copper with transistor	USPAT	OR	ON	2006/08/03 09:32
L143	1	"4939568".pn.	USPAT	OR	ON	2006/08/03 09:32
L144	1	"20040124538".pn.	US-PGPUB; USPAT; USOCR	OR	ON	2006/08/03 09:32
L145	1	"20040124538".pn.	US-PGPUB; USPAT; USOCR	OR	ON	2006/08/03 09:32
L146	1	"4939568".pn.	USPAT	OR	ON	2006/08/03 09:32
L147	1	"20040124538".pn.	US-PGPUB; USPAT; USOCR	OR	ON	2006/08/03 09:32

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L148	46	("20020050635" "20020077467" "20020109236" "20020109236" "20020135062" "4313126" "4402761" "4456888" "4599704" "4313126" "4402761" "4456888" "4599704" "4986861" "5523628" "5706578" "5767009" "5825080" "0050635" "5156997" "5206186" "5445994" "5523628" "5821138" "5923087" "6717244" "6441478" "6717244" "0077467").PN.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/08/03 09:32
L149	10	("4285780" "5072075" "5274912" "5590461").PN. OR ("5706578").URPN.	US-PGPUB; USPAT; USOCR	OR	ON	2006/08/03 09:32
L150	9	("3489954" "3533023" "4939568" "5311059" "5401687" "5438212" "5721454").PN.	US-PGPUB; USPAT; USOCR	OR	ON	2006/08/03 09:32
L151	92	("3787252" "4074342" "4500905" "4523211" "4688069" "4761681" "4807021").PN. OR ("4939568").URPN.	US-PGPUB; USPAT; USOCR	OR	ON	2006/08/03 09:32
L152	3	("5753536" "5902118" "6322903").PN.	US-PGPUB; USPAT; USOCR	OR	ON	2006/08/03 09:32
L153	3	wiring adj interconnect with copper with transistor	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/08/03 09:32
L154	8	("4461922" "4481378" "5398200" "5401983" "5612552" "5731621" "5747846" "5852310").PN.	US-PGPUB; USPAT; USOCR	OR	ON	2006/08/03 09:32
L155	5	("5753536" "5902118" "6322903").PN. OR ("6525415").URPN.	US-PGPUB; USPAT; USOCR	OR	ON	2006/08/03 09:32
L156	133	(three near2 dimensional near1 (IC integrated adj circuit chip die wafer semiconductor)).ab. and "257"/\$.ccls.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/08/03 09:32
L157	46	("20020050635" "20020077467" "20020109236" "20020109236" "20020135062" "4313126" "4402761" "4456888" "4599704" "4313126" "4402761" "4456888" "4599704" "4986861" "5523628" "5706578" "5767009" "5825080" "0050635" "5156997" "5206186" "5445994" "5523628" "5821138" "5923087" "6717244" "6441478" "6717244" "0077467").PN.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/08/03 09:32

EAST Search History

L158	92	("3787252" "4074342" "4500905" "4523211" "4688069" "4761681" "4807021").PN. OR ("4939568"). URPN.	US-PGPUB; USPAT; USOCR	OR	ON	2006/08/03 09:32
L159	9	("3489954" "3533023" "4939568" "5311059" "5401687" "5438212" "5721454").PN.	US-PGPUB; USPAT; USOCR	OR	ON	2006/08/03 09:32
L160	3	("5753536" "5902118" "6322903").PN.	US-PGPUB; USPAT; USOCR	OR	ON	2006/08/03 09:32
L161	46	("20020050635" "20020077467" "20 020109236" "20020109236" "20020 135062" "4313126" "4402761" "445 6888" "4599704" "4313126" "44027 61" "4456888" "4599704" "4986861" "5523628" "5706578" "5767009" "5 825080" "0050635" "5156997" "520 6186" "5445994" "5523628" "58211 38" "5923087" "6717244" "6441478" "6717244" "0077467").PN.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/08/03 09:32
L162	10	("4285780" "5072075" "5274912" "5590461").PN. OR ("5706578"). URPN.	US-PGPUB; USPAT; USOCR	OR	ON	2006/08/03 09:32
L163	92	("3787252" "4074342" "4500905" "4523211" "4688069" "4761681" "4807021").PN. OR ("4939568"). URPN.	US-PGPUB; USPAT; USOCR	OR	ON	2006/08/03 09:32
L164	9	("3489954" "3533023" "4939568" "5311059" "5401687" "5438212" "5721454").PN.	US-PGPUB; USPAT; USOCR	OR	ON	2006/08/03 09:32
L165	8	("4461922" "4481378" "5398200" "5401983" "5612552" "5731621" "5747846" "5852310").PN.	US-PGPUB; USPAT; USOCR	OR	ON	2006/08/03 09:32
L166	5	("5753536" "5902118" "6322903").PN. OR ("6525415"). URPN.	US-PGPUB; USPAT; USOCR	OR	ON	2006/08/03 09:32
L167	81	interconnect near3 copper with transistor	USPAT	OR	ON	2006/08/03 09:32
L168	46	("20020050635" "20020077467" "20 020109236" "20020109236" "20020 135062" "4313126" "4402761" "445 6888" "4599704" "4313126" "44027 61" "4456888" "4599704" "4986861" "5523628" "5706578" "5767009" "5 825080" "0050635" "5156997" "520 6186" "5445994" "5523628" "58211 38" "5923087" "6717244" "6441478" "6717244" "0077467").PN.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/08/03 09:32
L169	10	("4285780" "5072075" "5274912" "5590461").PN. OR ("5706578"). URPN.	US-PGPUB; USPAT; USOCR	OR	ON	2006/08/03 09:32

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L170	9	("3489954" "3533023" "4939568" "5311059" "5401687" "5438212" "5721454").PN.	US-PGPUB; USPAT; USOCR	OR	ON	2006/08/03 09:32
L171	2	("5940683").PN.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/08/03 09:32
L172	133	(three near2 dimensional near1 (IC integrated adj circuit chip die wafer semiconductor)).ab. and "257"/\$. ccls.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/08/03 09:32
L173	172	interconnect near3 copper with transistor	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/08/03 09:32
L174	172	interconnect near3 copper with transistor	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/08/03 09:32
L175	45	("4675717" "5270261" "5419806" "5426072" "5496743").PN. OR ("5902118").URPN.	US-PGPUB; USPAT; USOCR	OR	ON	2006/08/03 09:32
L176	2	"6677619".pn.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/08/03 09:32